

## High Linearity LNA Gain Block

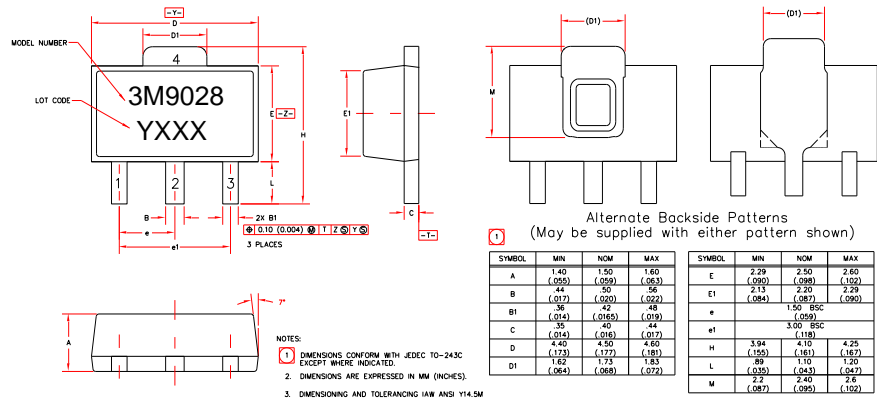


## Mechanical Information

## Package Information and Dimensions

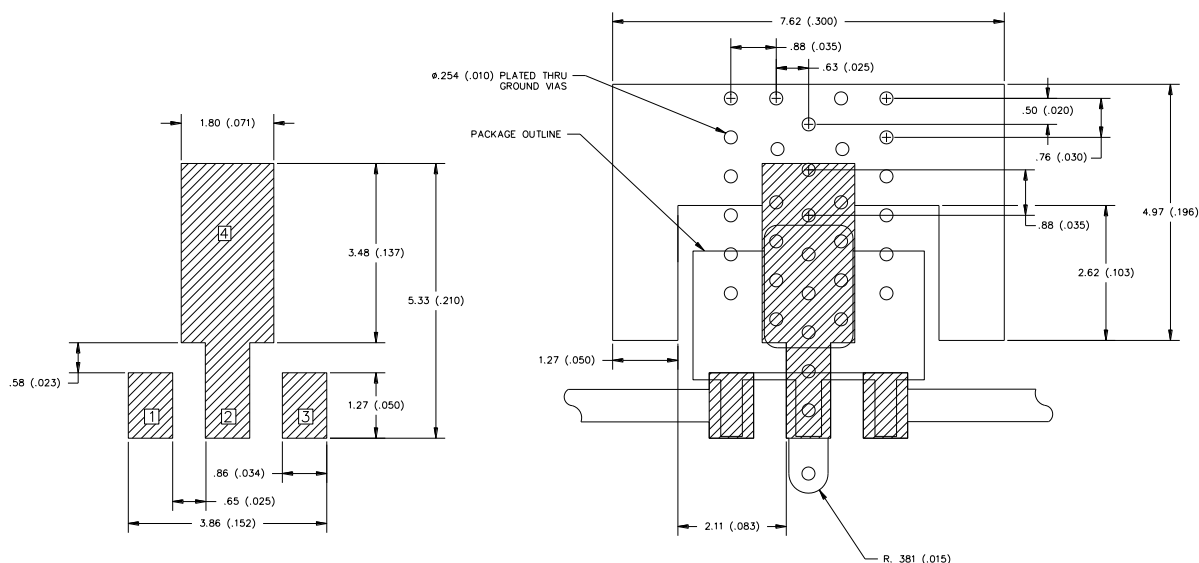
This package is lead-free/RoHS-compliant. The plating material on the leads is NiPdAu. It is compatible with both lead-free (maximum 260 °C reflow temperature) and lead (maximum 245 °C reflow temperature) soldering processes.

The component will be marked with a “3M9028” designator with an alphanumeric lot code on the top surface of package. The “Y” represents the last digit of the year the part was manufactured; the “XXX” is an auto generated number.



## Mounting Configuration

All dimensions are in millimeters (inches). Angles are in degrees.



Notes:

1. Ground / thermal vias are critical for the proper performance of this device. Vias should use a .35mm (#80 / .0135") diameter drill and have a final plated thru diameter of .25 mm (.010").
2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
3. RF trace width depends upon the PC board material and construction.
4. Use 1 oz. Copper minimum.